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Henry Helvajian
Hongqiang Chen
Editors

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Contents

vii	<i>Authors</i>
ix	<i>Conference Committee</i>

NEW TECHNOLOGIES IN DLW: JOINT SESSION WITH 10909 AND 10930

10909 03	Axial resolution improvement in multiphoton polymerization by 4Pi excitation [10909-2]
----------	---

POWDER-BED SLM METAL PRINTING

10909 07	A deep dive into metal 3D printing (Invited Paper) [10909-6]
10909 08	Influence of multi-spot exposure of powder bed on melt pool stability in selective laser melting [10909-7]
10909 09	Area melting with multi-laser arrays to increase build rate for metal powder bed fusion additive manufacturing [10909-8]
10909 0A	Concepts for integrating laser polishing into an additive manufacturing system [10909-9]

NEW TECHNOLOGY FOR COPPER PRINTING

10909 0C	Blues skies for copper cladding with 450nm (Invited Paper) [10909-11]
10909 0D	Additive manufacturing of pure copper using ultrashort laser pulses [10909-12]

MULTI-MATERIALS PRINTING

10909 0G	Individual material and process development in laser based additive manufacturing [10909-15]
10909 0H	Phenomena in multi-material fabrication using laser metal deposition (Invited Paper) [10909-16]

LASER CLADDING AND HOT WIRE PRINTING

- 10909 0J **Wire-based direct metal deposition with Ti6Al4V (Invited Paper)** [10909-17]
- 10909 0L **Additive manufacturing by wire based laser metal deposition (Invited Paper)** [10909-19]

PROCESS MONITORING AND CONTROL

- 10909 0M **Influence of energy input on spatter generation of 316L stainless steel fabrication by SLM in vacuum (Invited Paper)** [10909-20]
- 10909 0O **Layer-wise powder deposition defect detection in additive manufacturing** [10909-22]

NOVEL MATERIAL AND DEVICE PRINTING

- 10909 0P **Inkjet printing enabled rapid prototyping and model verification processes (Invited Paper)** [10909-24]
- 10909 0Q **Direct write of photonics using a filament-fed laser-heated process** [10909-25]

MICROPRINTING AND FORWARD TRANSFER

- 10909 0T **Femtosecond laser induced damage threshold (LIDT) of 3D nanolithography made micro- and nano-optical elements** [10909-28]

3D METROLOGY AND INSPECTION

- 10909 0V **Time-based offline track planning of robot guided laser applications for complex 3D freeform surfaces (Invited Paper)** [10909-30]
- 10909 0W **Irradiation angle dependence and polarization dependence in 3D geometry measurement using AMCW LiDAR** [10909-31]

POSTER SESSION

- 10909 0Y **Pure copper layer formation on copper based alloy substrate with 100 W class blue diode laser**
[10909-33]
- 10909 0Z **Effect of input energy on densification for pure copper fabricated by SLM with blue diode laser**
[10909-34]
- 10909 16 **Precise and large-dynamic-range surface profilometry using time-of-flight detection of femtosecond optical pulses** [10909-41]

Authors

Numbers in the index correspond to the last two digits of the seven-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first five digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Abe, N., 0Y	Marquardt, Franz, 0H
Arnaud, C., 0L	Masuno, S., 0Z
Bernthaler, T., 0G	Matthäus, Gabor, 0D
Bogdan, David, 09	McCarthy, Brian, 09
Börret, R., 0V	Mizeikis, Vyantas, 0T
Braun, M., 0V	Moroko, M., 0O
Bristow, Douglas, 0Q	Müller, Michael, 0H
Britten, Simon W., 0C	Na, Yongjin, 16
Brow, Richard, 0Q	Naidoo, Darryl, 0O
Brueckner, Frank, 0H	Ngoben, Chris, 0O
Butkutė, Agnė, 0T	Nolte, Stefan, 0D
Capps, Nicholas, 0Q	Ocylok, Sörn, 0C
Carter, William, 09	Ostroverkhov, Victor, 09
Chen, Ray T., 0P	Ploshikhin, V., 08
Davis, Thomas, 07	Pohl, M., 0V
Ding, Yaoyu, 0J	Purlys, Vytautas, 03
Funada, Y., 0Y	Ramm, Roland, 0D
Gadonas, Roldas, 03	Ramokolo, R., 0O
Gailevičius, Darius, 0T	Riede, Mirko, 0H
Goldstein, Jonathan, 0Q	Riegel, H., 0G, 0V
Graham, Michael, 09	Ruck, S., 0G, 0V
Grubb, Peter Mack, 0P	Sato, Yuji, 0M, 0Y, 0Z
Hata, T., 0Y	Schab, Johannes C., 0H
Hayashi, Neisei, 0W	Schanz, J., 0V
Hendriks, Adriaan, 0O	Schneider, G., 0G
Higasino, R., 0Y	Schubert, T., 0G
Hofele, M., 0G, 0V	Schurr, J., 0G
Hori, Eiji, 0M	Seidel, André, 0H
Hsu, Jen Hsien, 0Q	Sei, Sze Yun, 0W
Huang, Jie, 0Q	Seyfarth, Brian, 0D
Ilin, A., 08	Shi, Kebin, 16
Jeon, Chan-Gi, 16	Shibata, T., 0Z
Johnson, Jason E., 0Q	Slodczyk, M., 08
Jonušauskas, Linas, 0T	Srisawadi, Sasitorn, 0M
Kaden, Lisa, 0D	Subbaraman, Harish, 0P
Karp, Jason, 09	Tanprayoon, Dhriti, 0M
Kiedrowski, T., 08	Tičkūnas, Titas, 03
Kim, Jungwon, 16	Tsukamoto, Masahiro, 0M, 0Y, 0Z
Kinzel, Edward, 0Q	Ullsperger, Tobias, 0D
Kling, R., 0L	Valentin, M., 0L
Kolb, D., 0G	Yamashita, Shinji, 0W
Lachmayer, Roland, 0A	Zhang, Chao, 0W
Landers, Robert, 0Q	Zhu, Chen, 0Q
Leuteritz, Georg, 0A	
Leyens, Christoph, 0H	
Liu, Shuang, 0J	
López, Elena, 0H	
Lu, Xing, 16	
Malinauskas, Mangirdas, 0T	

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- 1 New Technologies in DLW: Joint Session with 10909 and 10930
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- 2 Novel Materials for DLW: Joint Session with 10909 and 10930
Harald Giessen, Universität Stuttgart (Germany)
- 3 Powder-bed SLM Metal Printing
Henry Helvajian, The Aerospace Corporation (United States)
- 4 New Technology for Copper Printing
Hongqiang Chen, GE Global Research (United States)
- 5 Multi-Materials Printing
Henry Helvajian, The Aerospace Corporation (United States)
- 6 Laser Cladding and Hot Wire Printing
Henry Peng, Institute of Applied Research on Intelligent Science & Technology (China)
- 7 Process Monitoring and Control
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- 8 Novel Material and Device Printing
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